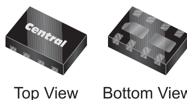
Material Composition Specification

TLM832DS Case



Device average mass . . . . **13.1 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped Si	2.29%	0.3	Si	7440-21-3	2.29%	0.3	22,901
bond wire	gold	0.46%	0.06	Au	7440-57-5	0.46%	0.06	4,580
leadframe	Cu alloy w/ silver plating	18.24%	2.39	Cu	7440-50-8	17.63%	2.31	176,336
				Fe	7439-89-6	0.4%	0.053	4,046
				Zn	7440-66-6	0.02%	0.003	229
				Ag	7440-22-4	.18%	0.023	1,756
die attach	silver epoxy	0.58%	0.076	epoxy resin	Proprietary	0.11%	0.015	1,145
				Ag	7440-22-4	0.47%	0.061	4,656
encapsulation*	EMC GREEN	77.97%	10.215	silica (fused)	60676-86-0	73.05%	9.57	730,534
				epoxy resin	29690-82-2	2.34%	0.307	23,435
				phenol resin	9003-35-4	2.34%	0.307	23,435
				carbon black	1333-86-4	0.24%	0.031	2,366
plating	matte tin	0.46%	0.06	Sn	7440-31-5	0.46%	0.06	4,580

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (11-January 2012)